

PCN-278877
Product Change Notice

Issue Date: 18-April-2024

Change Description:

IC die wafer process change.

Parts Affected:

HCPL-5300#100
HCPL-5300#200
HCPL-5300#300
HCPL-5300
HCPL-5301#100
HCPL-5301#200
HCPL-5301#300
HCPL-5301
5962-9685201HPA
5962-9685201HPC
5962-9685201HXA
5962-9685201HYA
5962-9685201HYC

Description and Extent of Change:

IC die wafer fabrication process changing from a solid planar source pre-deposition doping to a liquid source pre-deposition doping process. This changes the method of depositing phosphorus onto the wafers.

Class K products are not affected at this time.

Reasons for Change:

IC die wafer supplier manufacturing process change to enhance process uniformity and stability.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

The device specification will remain the same, which will ensure product electrical performance remains the same. Appropriate electrical characterization and reliability qualification has been performed on representative products to ensure normal parametric distribution, consistent electrical performance, and reliability.

There are no data sheet parameters affected by this change.

Effective Date of Change:

Estimated conversion August 2024.

GIDEP Product Change Notice, Document JL8-PC-2024-0001A.

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please acknowledge the receipt of the notice within 30 days of delivery. Lack of acknowledgement within 30 days constitutes acceptance of the change per JEDEC J-STD-046.